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RCE7/200  
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<b>REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL</b>  Subsection (b) of 35 U.S.C. § 132, effective on May 29, 2000, provides for continued examination of an utility or plant application filed on or after June 8, 1995. See The American Inventors Protection Act of 1999 (AIPA).	<b>Application Number</b>	09/649,827
	<b>Filing Date</b>	August 29, 2000
	<b>First Named Inventor</b>	Edward A. Schrock et al.
	<b>Group Art Unit</b>	1733
	<b>Examiner Name</b>	John J. Gallagher
	<b>Attorney Docket Number</b>	303.527US2

This is a Request for Continued Examination (RCE) under 37 C.F.R. § 1.114 of the above-identified application entitled  
METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE.

#13/609  
8/21/02

Submission required under 37 C.F.R. § 1.114

1. ☐ Consider the amendment(s)/reply under 37 C.F.R. § 1.116 previously filed on ☐
2. ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on ☐
3. ☒ A Supplemental Amendment Under 37 CFR § 1.116 (11 pages) is enclosed.
4. ☐ A new power of attorney (☐ pages) is enclosed.
5. ☐ An Information Disclosure Statement is enclosed (☐ pages)
  - a. ☐ Form(s) 1449
  - b. ☐ Copies of IDS Citations
6. ☒ A check in the amount of \$740.00 is attached to pay the RCE filing fee required under C.F.R. § 1.17(e).
7. ☒ The Commissioner is hereby authorized to credit overpayments or charge any fees set forth in 37 C.F.R. §§ 1.16 through 1.18 to Deposit Account No. 19-0743.
8. ☒ A petition for extension of time in the prior application (☐ pages) is enclosed along with a check in the amount of \$110.00 to pay the extension fee.
9. ☒ Other: A Clean Version of Amended Specification Paragraphs (1pg.); A Clean Version of Pending Claims (6 pgs.)

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**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Box RCE, Washington, D.C. 20231, on this 9th day of August, 2002.

Name Amy Moriarty

Signature Amy Moriarty

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EXPEDITED PROCEDURE - EXAMINING GROUP 1733

#74/E  
JAE

PATENT

8/21/02

09/649,827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Edward A. Schrock et al.

Examiner: John J. Gallagher

Serial No.: 09/649,827

Group Art Unit: 1733

Filed: August 29, 2000

Docket: 303.527US2

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

SUPPLEMENTAL AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116

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Commissioner for Patents  
Washington, D.C. 20231

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TC 1700

Applicant has reviewed the Final Office Action mailed April 9, 2002, and the Advisory Office Action mailed July, 8, 2002. Please amend the application as follows:

IN THE SPECIFICATION

Please substitute the paragraph in the appendix entitled "Clean Version of Page 10, Paragraph 2" for page 10, paragraph 2 beginning on line 9. Specific amendments to page 10, paragraph 2 beginning on line 9 are detailed in the following marked-up paragraph:

The adhesive layer(s) 46, 48 may be responsive to heat, pressure, or both. In one embodiment, the heat responsive component is a [thermoset] thermosetting material. The [thermoset] thermosetting material may be a "B-stageable" material (i.e., having an intermediate stage in which the material remains wholly or partially plastic and fusible so that it softens when heated). In yet another embodiment, the heat responsive component is a thermoplastic material.